MMBD352LT1, MMBD353LT1, MMBD354LT1. MMBD355LT1

Dual Hot Carrier Mixer Diodes

These devices are designed primarily for UHF mixer applications but are suitable also for use in detector and ultra-fast switching circuits.

Features

- Very Low Capacitance Less Than 1.0 pF @ Zero V
- Low Forward Voltage 0.5 V (Typ) @ $I_F = 10 \text{ mA}$
- Pb-Free Packages are Available

MAXIMUM RATINGS (EACH DIODE)

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V _R	7.0	V _{CC}

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	–55 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.

2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.

ELECTRICAL CHARACTERISTICS (T _A = 25°C unless otherwise note	ed)
(EACH DIODE)	

Rating	Symbol	Min	Max	Unit
Forward Voltage (I _F = 10 mAdc)	VF	-	0.60	V
Reverse Leakage Current (Note 3) $(V_R = 3.0 V)$ $(V_R = 7.0 V)$	I _R	-	0.25 10	μΑ
Capacitance (V _R = 0 V, f = 1.0 MHz)	С	-	1.0	pF

3. For each individual diode while the second diode is unbiased.

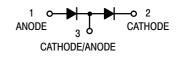
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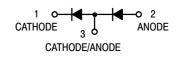
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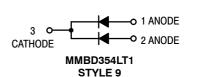


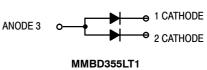






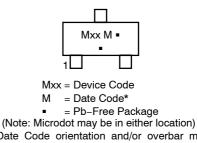
MMBD353LT1 STYLE 19





STYLE 12

MARKING DIAGRAM

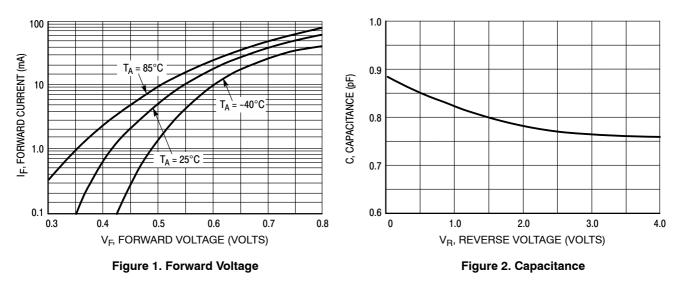


*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering, marking, and shipping information in the package dimensions section on page 2 of this data sheet.

MMBD352LT1, MMBD353LT1, MMBD354LT1, MMBD355LT1



TYPICAL CHARACTERISTICS

ORDERING INFORMATION

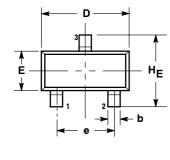
Device	Marking	Package	Shipping [†]		
MMBD352LT1		SOT-23	3,000 Units / Tape & Reel		
MMBD352LT1G		SOT-23 (Pb-Free)	3,000 Units / Tape & Reel		
MMBD352LT3	M5G -	SOT-23	10,000 Units / Tape & Reel		
MMBD352LT3G]	SOT-23 (Pb-Free)	10,000 Units / Tape & Reel		
MMBD353LT1		SOT-23	3,000 Units / Tape & Reel		
MMBD353LT1G]	SOT-23 (Pb-Free)	3,000 Units / Tape & Reel		
MMBD353LT3	M4F	SOT-23	10,000 Units / Tape & Reel		
MMBD353LT3G]	SOT-23 (Pb-Free)	10,000 Units / Tape & Reel		
MMBD354LT1		SOT-23	3,000 Units / Tape & Reel		
MMBD354LT1G	М6Н	SOT-23 (Pb-Free)	3,000 Units / Tape & Reel		
MMBD355LT1		SOT-23	3,000 Units / Tape & Reel		
MMBD355LT1G	MJ1	SOT-23 (Pb-Free)	3,000 Units / Tape & Reel		

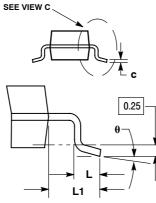
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MMBD352LT1, MMBD353LT1, MMBD354LT1, MMBD355LT1

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 ISSUE AN





VIEW C

NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD

LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF

BASE MATERIAL

4. 318-01 THRU -07 AND -09 OBSOLETE

NEW STANDARD 318-08.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
с	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

MMBD352LT1

STYLE 11:

PIN 1. ANODE 2. CATHODE

3. CATHODE-ANODE

MMBD353LT1

STYLE 19: PIN 1. CATHODE

2. ANODE 3. CATHODE-ANODE

MMBD354LT1

STYLE 9:

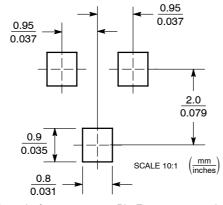
PIN 1. ANODE 2. ANODE 3. CATHODE

MMBD355LT1

STYLE 12: PIN 1. CATHODE 2. CATHODE

3. ANODE

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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